IN THE CLAIMS

1. (currently amended): An interposer for providing electrical connections between lands of a Land Grid Array (LGA) device and corresponding lands of an electronic assembly, said interposer comprising:

an interposer frame comprising a substantially planar insulating sheet defining dumbell-shaped voids through said insulating sheet perpendicular to a primary plane of the interposer frame, said voids provided for the insertion of contacts spaced in a grid-array;

a plurality of flexible C-shaped metal conductive contacts each having an arcuate first contact end and an arcuate second contact end, and wherein said contacts are inserted within and through the voids defined by said interposer frame such that said first contact extends above a top surface of said interposer frame and said second contact extends below a bottom surface of said interposer frame, and a gap of the C-shape is between the top surface and the bottom surface; and

an elastic disposed between said contacts and said interposer frame and adhered to said interposer frame, whereby said contacts are mechanically retained to said interposer frame by said elastic which permits travel of said contacts in a direction perpendicular to said interposer frame via flexure of said elastic.

2. (previously presented): The interposer of Claim 1, wherein said elastic is disposed completely around a periphery of a portion of said voids and said contacts, said portion being located within said voids between said top surface and said bottom surface of said interposer frame, whereby said contacts are surrounded by said elastic and retained to said interposer by said elastic.

3. (previously presented): The interposer of Claim 1, wherein said elastic is disposed partially around a periphery of a portion of said voids and said contacts, said portion being located within said voids between said top surface and said bottom surface of said interposer frame, whereby said contacts are surrounded by said elastic and retained to said interposer by said elastic .

4. (withdrawn): The interposer of Claim 1, wherein said contacts are spring contacts comprising a curved metal form.

5. (withdrawn): The interposer of Claim 4, wherein said elastic is disposed only within a central portion of said curved metal form and wherein said elastic is bonded to said interposer frame in a direction perpendicular to a direction of curvature of said contacts, whereby said contacts are retained.

6. (withdrawn): The interposer of Claim 5, wherein said elastic is adhered to said contacts, whereby said contacts are retained within said interposer frame.

7. (withdrawn): The interposer of Claim 5, wherein said elastic is a self-healing elastic, whereby said contacts are be inserted in said voids after cure of the elastic, whereby said contacts are retained by displacement of said elastic.

8.-16. (canceled)

17. (previously presented): An interposer for providing electrical connections between lands of a Land Grid Array (LGA) device and corresponding lands of an electronic assembly, said interposer comprising:

an interposer frame comprising a substantially planar insulating sheet defining voids through said insulating sheet perpendicular to a primary plane of the interposer frame, said voids provided for the insertion of contacts spaced in a grid-array;

a plurality of flexible C-shaped metal conductive contacts each having an arcuate first contact end and an arcuate second contact end, and wherein said contacts are inserted within and through the voids defined by said interposer frame such that said first contact extends above a top